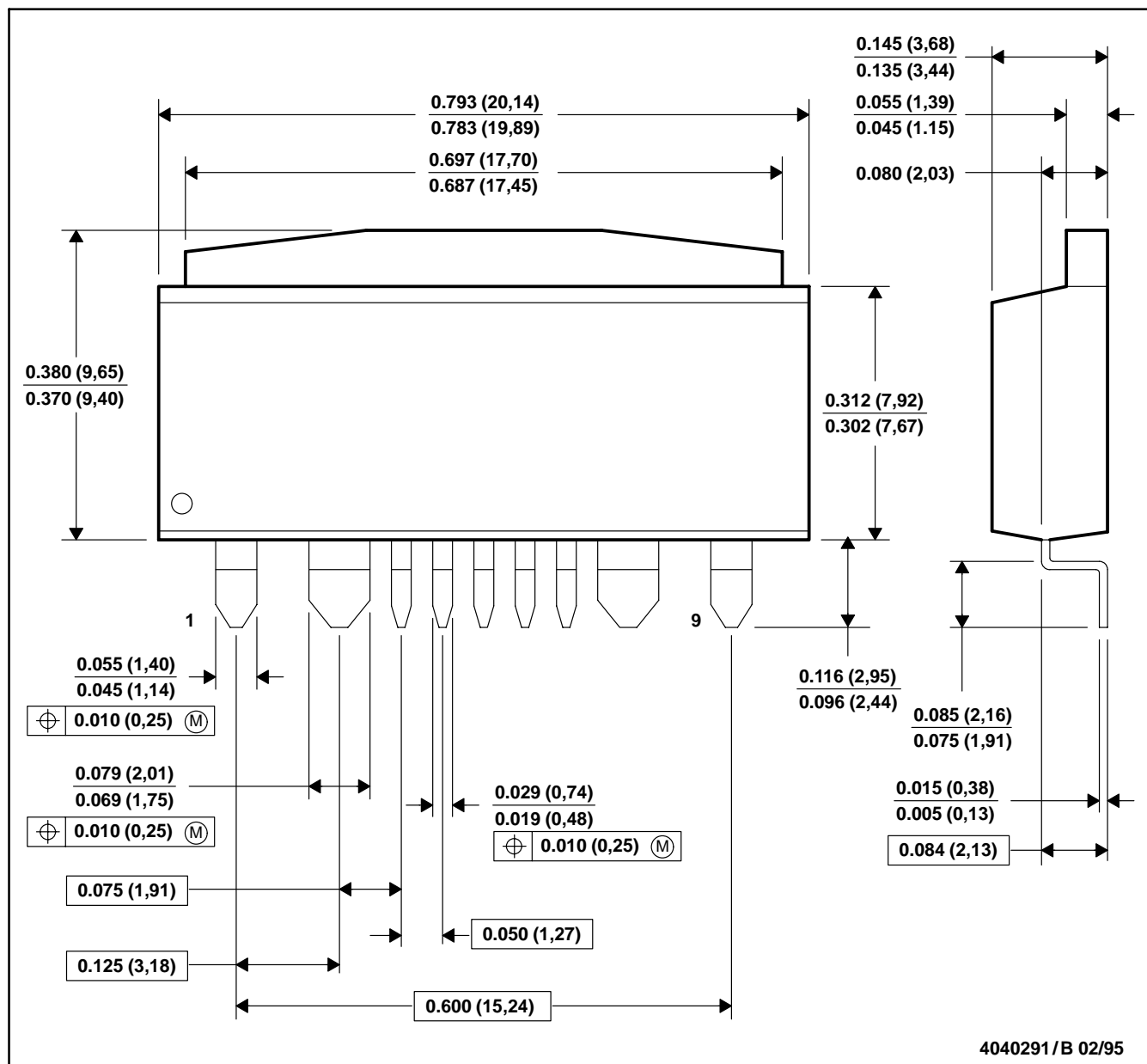


## KGC (R-PSFM-G9)

## PLASTIC FLANGE-MOUNT PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).  
 B. This drawing is subject to change without notice.  
 C. All dimensions apply before solder dip.  
 D. Leads 2 and 8 are in electrical contact with the mounting tab.

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